

## Extended Power IR Emitting Diode in SMD Package

### Description

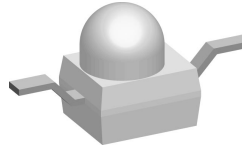
TSML10.0 is a high efficiency infrared emitting diode in GaAIAs on GaAs technology molded in clear SMD package

This technology represents best performance for radiant power under pulse conditions, forward voltage and reliability.

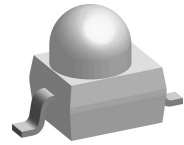
### Features

- Outstanding high radiant power
- Low forward voltage
- Suitable for high pulse current operation
- Angle of half intensity  $\phi = \pm 12^\circ$
- Peak wavelength  $\lambda_p = 950 \text{ nm}$
- High reliability
- Matched with Phototransistor TEMT1...series
- Versatile terminal configurations

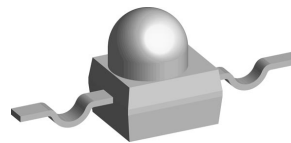
TSML1000



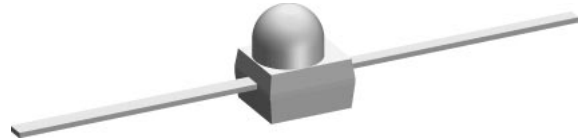
TSML1020



TSML1030



TSML1040



16758

### Applications

For remote control  
 Photointerrupters  
 Punched tape readers  
 Encoder

### Absolute Maximum Ratings

$T_{amb} = 25^\circ\text{C}$

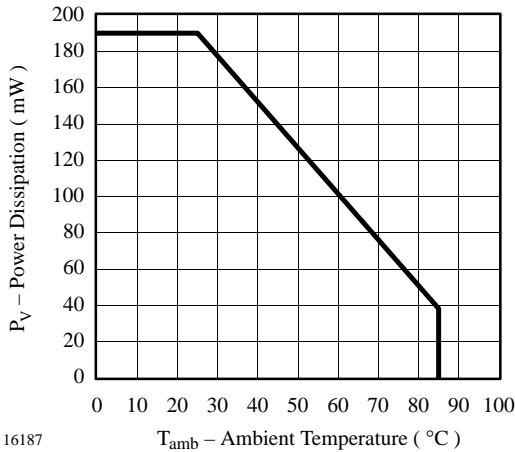
Parameter	Test Conditions	Symbol	Value	Unit
Reverse Voltage		$V_R$	5	V
Forward Current		$I_F$	100	mA
Peak Forward Current	$t_p/T = 0.5, t_p = 100 \mu\text{s}$	$I_{FM}$	200	mA
Surge Forward Current	$t_p = 100 \mu\text{s}$	$I_{FSM}$	1.0	A
Power Dissipation		$P_V$	190	mW
Junction Temperature		$T_j$	100	$^\circ\text{C}$
Operating Temperature Range		$T_{amb}$	-40...+85	$^\circ\text{C}$
Storage Temperature Range		$T_{stg}$	-40...+100	$^\circ\text{C}$
Soldering Temperature	$t \leq 5\text{sec}, 2 \text{ mm from case}$	$T_{sd}$	260	$^\circ\text{C}$
Thermal Resistance Junction/Ambient		$R_{thJA}$	400	$^\circ\text{C}$

### Basic Characteristics

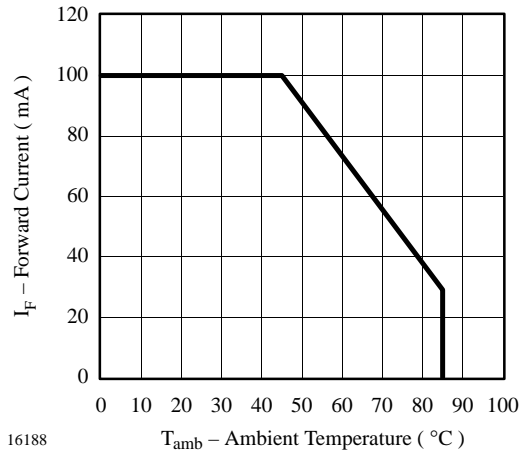
$T_{amb} = 25^{\circ}\text{C}$

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Forward Voltage	$I_F = 20\text{ mA}, t_p = 20\text{ ms}$	$V_F$		1.2	1.5	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$			2.4		
Temp. Coefficient of $V_F$	$I_F = 100\text{ mA}$	$TK_{V_F}$		-1.3		mV/K
Reverse Current	$V_R = 5\text{ V}$	$I_R$			10	$\mu\text{A}$
Junction Capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0$	$C_j$		25		pF
Radiant Intensity	$I_F = 20\text{ mA}, t_p = 20\text{ ms}$	$I_e$		7		mW/sr
Radiant Power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	$\Phi_e$		35		mW
Temp. Coefficient of $\Phi_e$	$I_F = 20\text{ mA}$	$TK_{\Phi_e}$		-0.6		%/K
Angle of Half Intensity		$\phi$		$\pm 12$		deg
Peak Wavelength	$I_F = 100\text{ mA}$	$\lambda_p$		940		nm
Spectral Bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$		50		nm
Temp. Coefficient of $\lambda_p$	$I_F = 100\text{ mA}$	$TK_{\lambda_p}$		0.2		nm/K
Rise Time	$I_F = 100\text{ mA}$	$t_r$		800		ns
Fall Time	$I_F = 100\text{ mA}$	$t_f$		800		ns

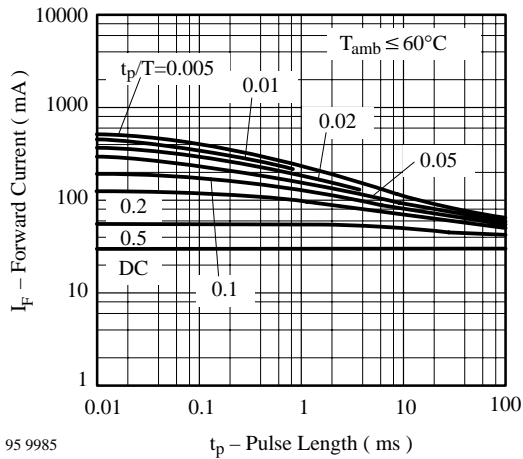
### Typical Characteristics ( $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)



16187  
Figure 1. Power Dissipation vs. Ambient Temperature

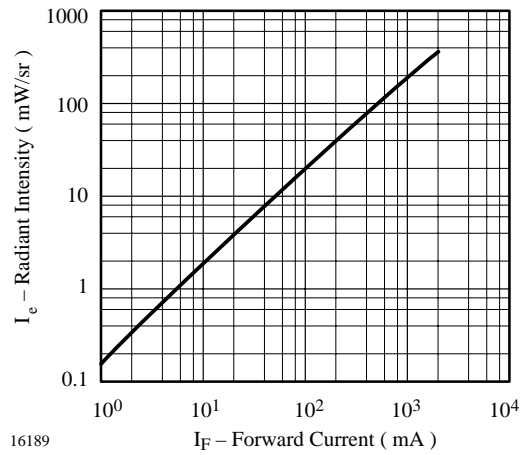


16188  
Figure 2. Forward Current vs. Ambient Temperature



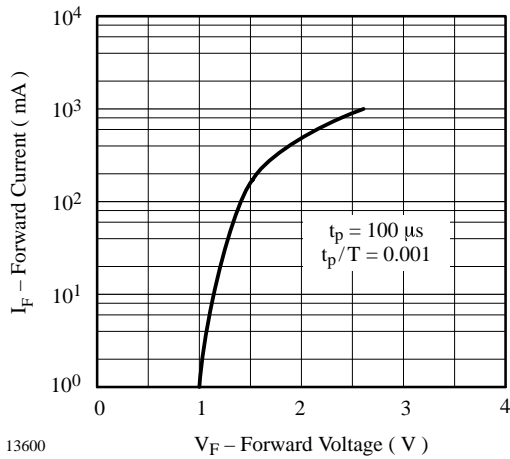
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Figure 3. Pulse Forward Current vs. Pulse Duration



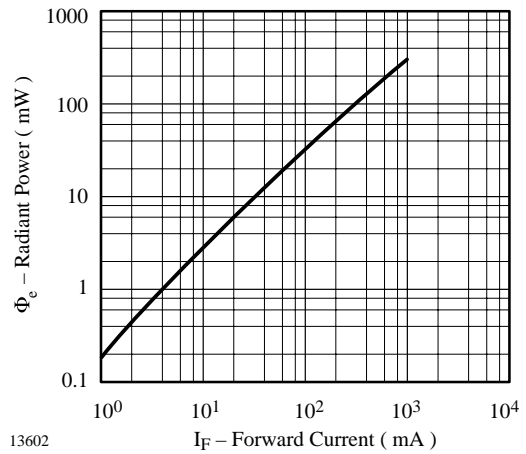
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Figure 6. Radiant Intensity vs. Forward Current



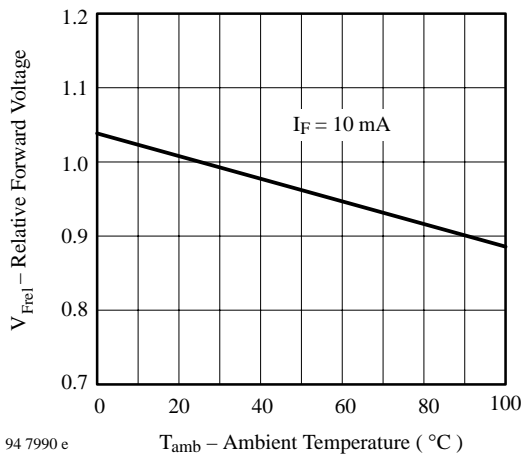
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Figure 4. Forward Current vs. Forward Voltage



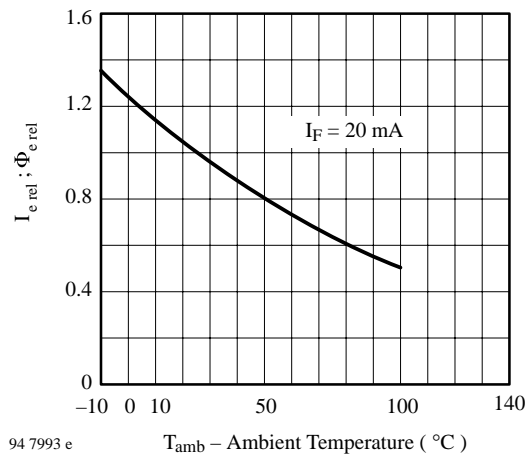
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Figure 7. Radiant Power vs. Forward Current



94 7990 e

Figure 5. Relative Forward Voltage vs. Ambient Temperature



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Figure 8. Rel. Radiant Intensity/Power vs. Ambient Temperature

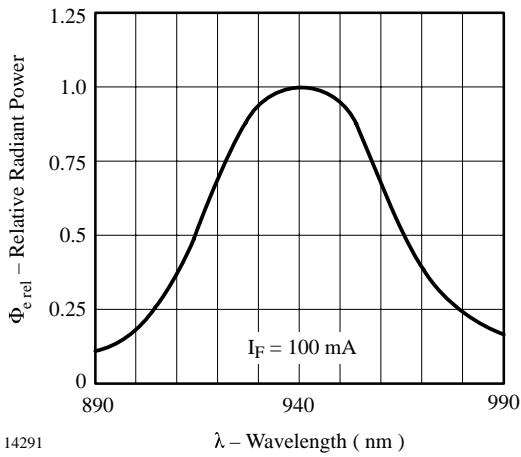


Figure 9. Relative Radiant Power vs. Wavelength

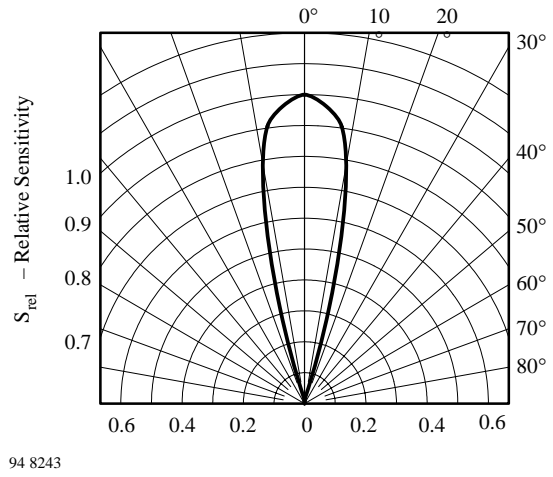
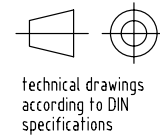
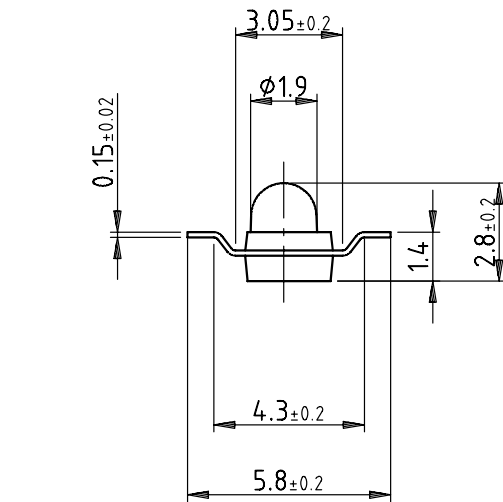
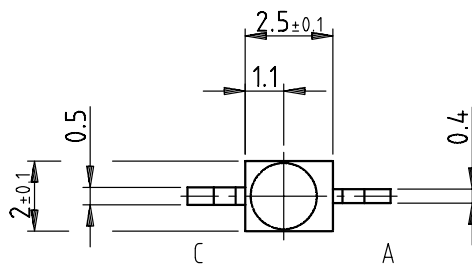


Figure 10. Relative Radiant Sensitivity vs. Angular Displacement

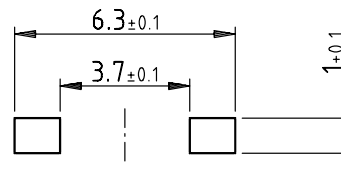
### Dimensions in mm of TSML1000



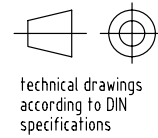
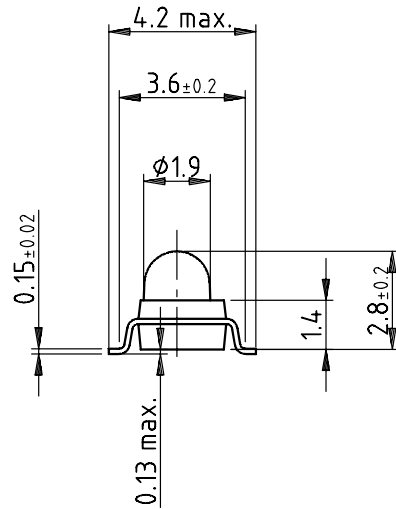
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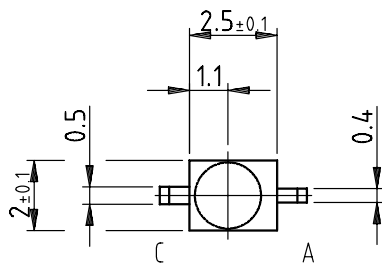
Solder pad proposal



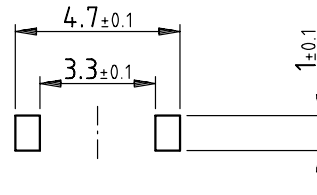
## Dimensions in mm of TSML1020



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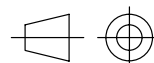
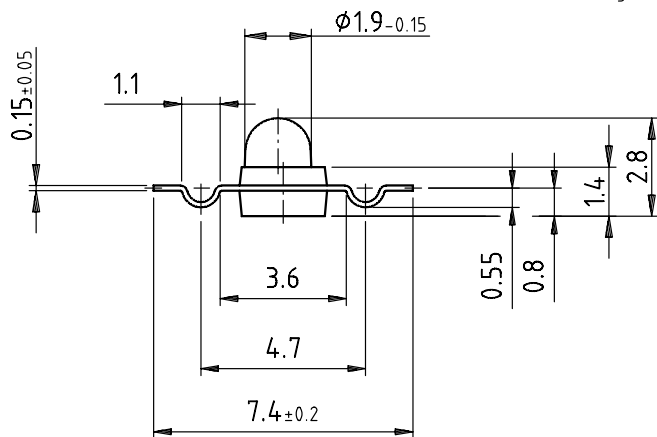


Solder pad proposal



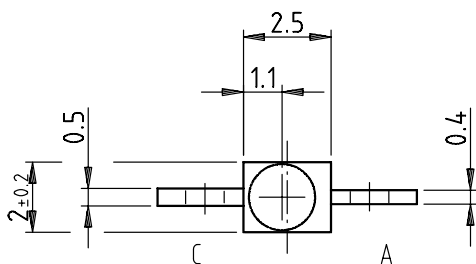
### Dimensions in mm of TSML1030

All dimensions in mm  
Not indicated tolerances  $\pm 0.1$   
Angle  $\pm 5^\circ$

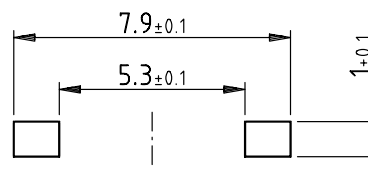


technical drawings  
according to DIN  
specifications

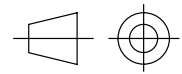
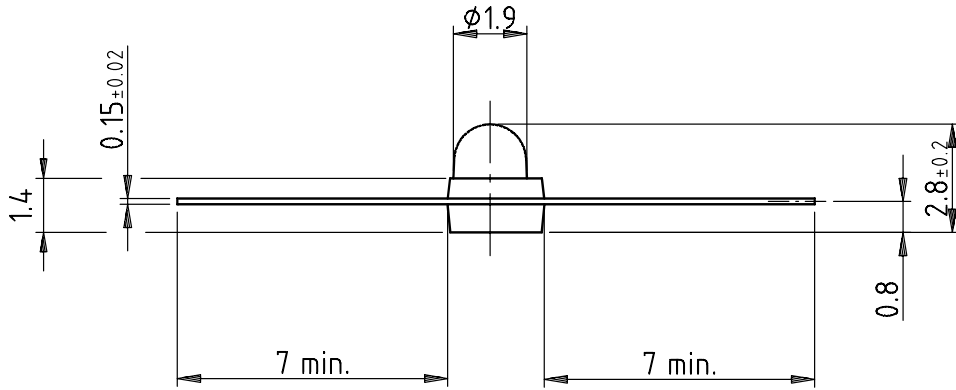
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Solder pad proposal

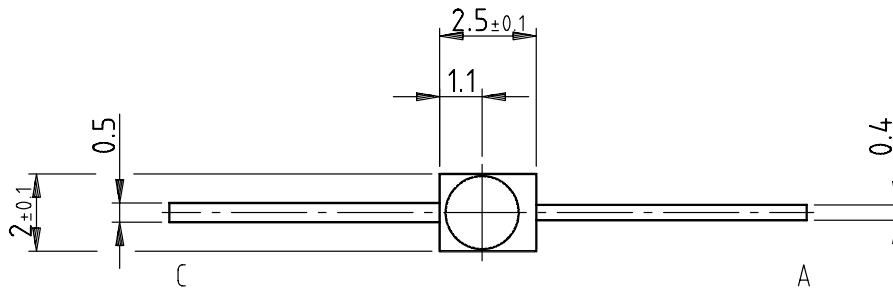


**Dimensions in mm of TSML1040**



technical drawings  
according to DIN  
specifications

16760



### Ozone Depleting Substances Policy Statement

It is the policy of **Vishay Semiconductor GmbH** to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**Vishay Semiconductor GmbH** has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**Vishay Semiconductor GmbH** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

**We reserve the right to make changes to improve technical design and may do so without further notice.**

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay-Telefunken products for any unintended or unauthorized application, the buyer shall indemnify Vishay-Telefunken against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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